EOS/ESD Symposium Outstanding Paper (Best Presentation) Awards

1983  “The Room Air Ionization System, a Better Alternative than 40% Relative Humidity”  
       C. F. Mykkanen and D.R. Blinde

1984  “The Effectiveness of Antistatic Bags in Screening Semiconductor Components Against ESD Transients”  
       G.C. Holmes

1984  “A Realistic and Systematic ESD Control Plan”  
       G.T. Dangelmayer

1985  “A Technique for Real-Time Examination of Sub-Surface EOS/ESD Damage in Integrated Circuits”  
       C.T. Amos and C.E. Stephens

1986  “Thick Oxide Device ESD Performance Under Process Variations”  
       R.A. Mc Phee, C. Duvvury, R.N. Rountree, H. Domingos

1987  “ESD Protection Structures to Survive the Charged Device Model (CDM)”  
       L.R. Avery

       Robert Rountree, Charvaka Duvvury, Tatsuro Maki, Harvey Stiegler

1988  “Triboelectricity and Surface Resistivity Do Not Correlate”  
       Steven L. Fowler

1989  “Understanding Pink Poly”  
       Marvin R. Havens

1990  “Electrostatic Discharge Protection for a 4-Mbit DRAM”  
       Mark D. Jaffe

       Joanne Woodward-Jack

1992  “ESD Protection In a 3.3V Sub-Micron Silicided CMOS Technology”  
       David Krakauer and Kaizod Mistry
1993  “The Identification and Analysis of Latent ESD Damage on CMOS Input Gates”
Jim Colvin

1994  “The Impact of Technology Scaling on ESD Robustness and Protection Circuit Design”
Ajith Amerasekera and Charvaka Duvvury

1995  “Advanced CMOS protection Device Trigger Mechanisms During CDM”
Charvaka Duvvury and Ajith Amerasekera

1996  “Recommendations to Further Improvements of HBM ESD Component Specifications”
Koen Verhaege, Christian Russ, G. Groeseneken, Donna Robinson-Hahn, Don Lin, Marty Farris, Jeff Scanlon, J.Veltri

1997  “ESD Robustness and Scaling Implications of Aluminum and Copper Interconnects in Advanced SemiConductor Technology”
Steven Voldman

1998  “Magneto Optical Static Event Detector”
N. Jacksen, Wayne Tan, Don Boehm

1999  “An Anti-Snapback Circuit Technique for Inhibiting Parasitic Bipolar Conduction During EOS/ESD Events”
Jeremy Smith

2000  “Wafer Cost Reduction through Design of High Performance Fully Silicided ESD Devices”
Koen Verhaege, Christian Russ

2001  “Multi-Finger Turn-on Circuits and Design Techniques for Enhanced ESD Performance and Width-Scaling”

2002  "Efficient pnp Characteristics of pMOS Transistors in Sub-0.13 μm ESD Protection Circuits"
G. Boselli, C. Duvvury, V. Reddy, Texas Instruments Inc.

2003  "Boosted and Distributed Rail Clamp Networks for ESD Protection in Advanced CMOS Technologies"

2004  "Engineering Single NMOS and PMOS Output Buffers for Maximum Failure Voltage in Advanced CMOS Technologies"
M.G. Khazhinsky, J.W. Miller, M. Stockinger, J.C. Weldon Freescale Semiconductor, Inc.
2005  Analysis of ESD Protection Components in 65nm CMOS Technology: Scaling Perspective and Impact on ESD Design Window
G. Boselli, J. Rodríguez, C. Duvvury, J. Smith, Texas Instruments, Inc.

2006  HBM Stress of No-Connect IC Pins and Subsequent Arc-Over Events that Lead to Human-Metal-Discharge-Like Events into Unstressed Neighbor Pins

2007  CDM Peak Current Variations and Impact Upon CDM Performance Thresholds
Agha Jahanzeb, Yen-Yi Lin, Steve Marum, Joe Schichl, Charvaka Duvvury

2008  HBM ESD Failures Caused by a Parasitic Pre-Discharge Current Spike
Melanie Etherton, James Miller, Freescale Semiconductor, Inc.; Victor Axelrod, Haim Marom, Freescale Semiconductor Isreal; Tom Meuse, Thermo Fisher Scientific

2009  A DRC-based Check Tool for ESD Layout Verification

2010  The Relevance of Long-Duration TLP Stress on System Level ESD Design
Gianluca Boselli, Akram Salman, Jonathan Brodsky, and Hans Kunz, Texas Instruments, Inc.

2011  Voltage Monitor Circuit for ESD Diagnosis
Nathan Jack, Elyse Rosenbaum, University of Illinois at Urbana-Champaign

2012  Chasing a Latent CDM ESD Failure by Unconventional FA Methodology
Harshit Dhakad, Harald Gossner, Bernhard Stein, Christian Russ, Intel Mobile Communications; Stefan Zekert, Infineon Technologies

2013  An Active MOSFET Rail Clamp Network for Component and System Level Protection
Michael Stockinger, Wenzhong Zhang, Kristen Mason, James Feddeler, Freescale Semiconductor, Inc.

2014  Do Devices on PCBs Really See a Higher CDM-like ESD Risk?
Reinhold Gärtner, Infineon Technologies; Wolfgang Stadler, Josef Niemesheim, Oliver Hilbricht, Intel Mobile Communications

2015  Low Impedance Contact CDM
Nathan Jack, Timothy J. Maloney, Intel Corporation

2016  EDA Approaches in Identifying Latch-up Risks
Michael Khazhinsky, Silicon Labs; Kzysztof Domanski, Harald Gossner, Intel Deutschland GmbH; Guido Quax, Scott Ruth, NXP Semiconductors; Farzan Farbiz, Texas Instruments; Nitesh Trivedi, Infineon
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<th>Year</th>
<th>Title</th>
<th>Authors</th>
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<tr>
<td>2016</td>
<td>Predict the Product Specific CDM Stress Using Measurement-Based Models of CDM Discharge Heads</td>
<td>Friedrich zur Nieden, Kai Esmark, Stefan Seidl, Reinhold Gärtner</td>
<td>Infineon Technologies AG</td>
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<td>2017</td>
<td>FinFET SCR: Design Challenges and Novel Fin SCR Approaches for On-Chip ESD Protection</td>
<td>Milova Paul, B. Sampath Kumar, Mayank Shrivastava, Indian Institute of Science; Christian Russ, Harald Gossner</td>
<td>Intel Deutschland GmbH</td>
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<td>2018</td>
<td>Study of the Discharge Current Created by an Ionizer</td>
<td>Stefan Seidl, Friedrich zur Nieden, Reinhold Gaertner</td>
<td>Infineon Technologies AG</td>
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<td>2018</td>
<td>Undesired Effects of CDM Stressing Non-Connected Pins</td>
<td>Theo Smedes, Bob Knoppers, Richard Derikx, NXP Semiconductors; Artemio Garcia, Greg O'Sullivan</td>
<td>Micron Technology</td>
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